

FORM PTO-1449
(REV. 7-80)US. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
RD-28435SERIAL NO.
09/681,304INFORMATION DISCLOSURE STATEMENT BY APPLICANT
LIST OF ITEMSApplicant
RICHARD J. SAIA, ET ALFiling Date
3/15/01

Group

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
DLN	AA 5,161,093	11/3/92	GORCZYCA, ET AL			
DLN	AB 5,353,498	10/11/94	FILLION, ET AL			
DLN	AC 5,527,741	6/18/96	COLE, ET AL			
DLN	AD 6,150,719	11/21/00	SAIA, ET AL			
	AE					

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	B1					
	B2					
	B3					

OTHER INFORMATION (Including Author, Title, Date, Pertinent Pages, etc.)

DLN	C1	US PATENT APPLICATION, SER. NO. 09/399,461, FILED 9/20/99, ENTITLED "HDI CHIP ATTACHMENT METHOD FOR REDUCED PROCESSING" BY EL BALCH, ET AL, (ATTORNEY DOCKET NO. RDMM25449).
DLN	C2	US PATENT APPLICATION, SER. NO. 09/411,101, FILED 10/99, ENTITLED "CIRCUIT CHIP PACKAGE AND FABRICATION METHOD" BY FILLION, ET AL, (ATTORNEY DOCKET NO. RD-26,569).
DLN	C3	US PATENT APPLICATION, SER. NO. 09/469,749, FILED 12/22/99, ENTITLED " APPARATUS, METHOD AND PRODUCT THEREFROM, FOR ALIGNING DIE TO INTERCONNECT METAL ON FLEX SUBSTRATE" (ATTORNEY DOCKET NO. RD-26,951).
DLN	C4	JT BUTLER, ET AL, "ADAPTING MULTICHIP MODEL FOUNDRIES FOR MEMS PACKAGING", <i>INTERNATIONAL JOURNAL OF MICROCIRCUITS AND ELECTRONIC PACKAGING</i> , VOL. 21, NO. 2, 6 PAGES, 2 ND QTR. 1998.
DLN	C5	AD WOLFRUM, SHIPLEY MULTIPOSIT XP-9500 CC-1 PHOTODIELECTRIC, 4 PAGES, 1995.

EXAMINER

DATE CONSIDERED

*Richard Nuyes**3/20/02*

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant